

RoHS
Compliant

Specifications

Dice material	: AlGaInP/GaAs
Emmiting Colour	: Super Red
Lens colour	: Water clear
Peak wavelength	: 632nm
Viewing angle	: 130°
Luminous intensity (IV)	: 90mcd

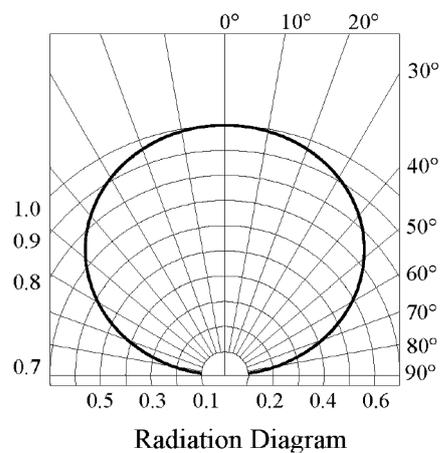
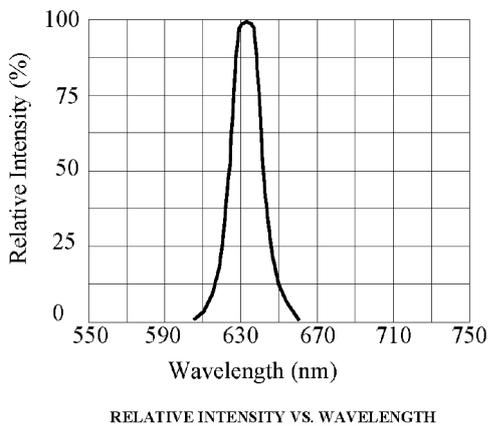
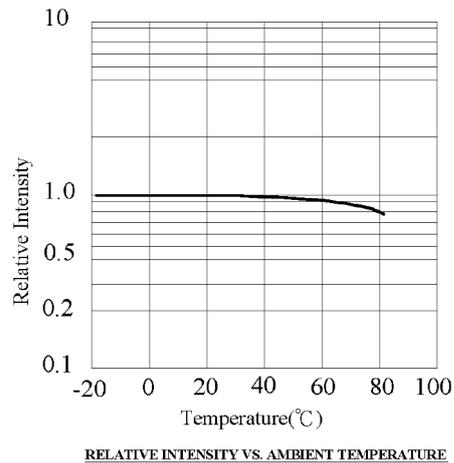
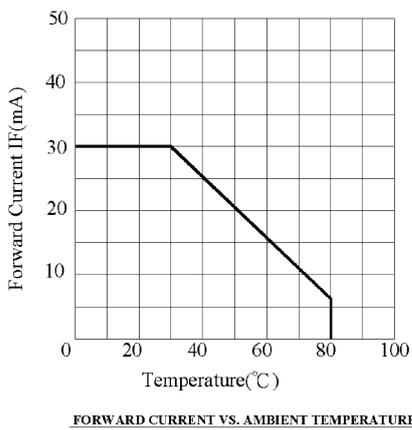
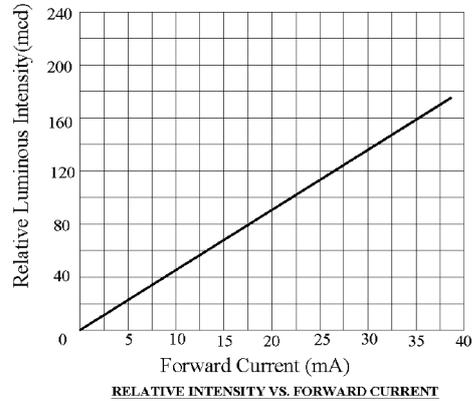
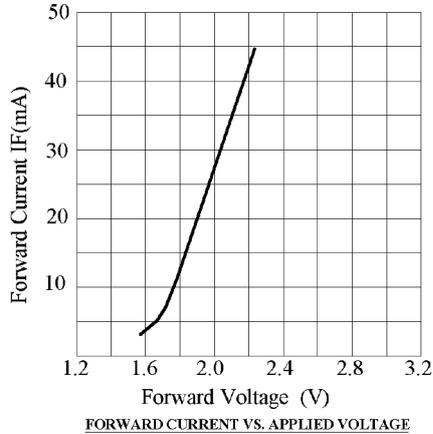
Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Unit
Power Dissipation	PD	72	mW
D.C Forward current	If	30	mA
Reverse Voltage	Vr	5	V
Operating Temperature	Top	-30 to +80	°C
Storage Temperature	Tstg.	-40 to +85	°C
Peak Current (1/10Duty Cycle, 0.1ms Pulse Width.)	If (peak)	80	mA
Soldering Temperature	Tsol	Reflow Soldering: 260°C for 10 sec.	

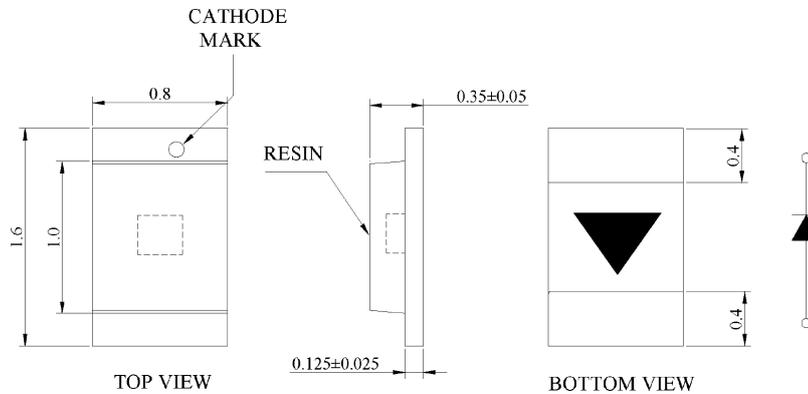
Electrical and Optical Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	Iv	If=20mA	42.9	90		mcd
Forward Voltage	Vf	If=20mA		1.9	2.4	V
Peak Wavelength	λ_p	If=20mA		632		nm
Dominant Wavelength	λ_d	If=20mA		624		nm
Reverse Current	Ir	Vr=5V			100	μ A
Viewing Angle	2 θ 1/2	If=20mA		130		deg
Spectrum Line Halfwidth	$\Delta\lambda$	If=20mA		20		nm

Typical Electrical/Optical Characteristic Curves:



Dimensions



Tolerance is ± 0.1 mm unless otherwise noted.

Dimensions : Millimetres

Precautions in use:

Storage

Recommend storage environment:

Temperature: 5°C to 30°C (41°F to 86°F)

Humidity: 60% RH Max.

Use within 7 days after opening of sealed vapor/ESD barrier bags. Fold the opened bag firmly and keep in dry environment.

Soldering

Reflow Soldering

Recommend use of upper and lower heater type reflow furnace.

260°C Max for up to 5 seconds, one time only.

Pre-heat is 150°C Max for up to 2 minutes Max.

In case of screen-printing, keep metal mask thickness between 0.2mm and 0.3mm.

Manual Iron Soldering (NOT RECOMMENDED)

Use SN60 solder or solder with silver content.

Use 25W soldering iron at 300°C (570°F) Max for 5 seconds or less. Must not touch top resin portion of SMD

LED by heated soldering iron.

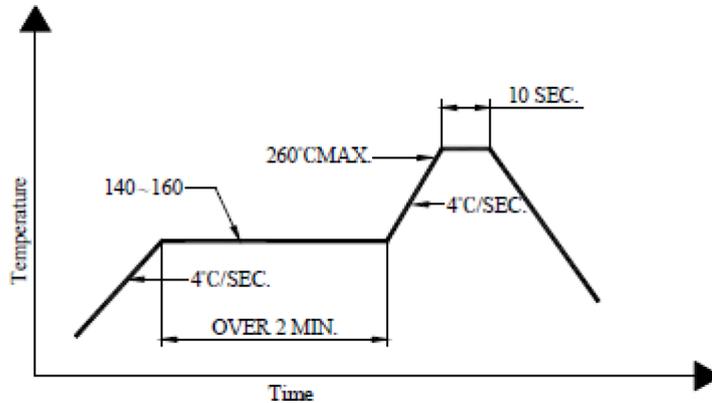
Cleaning

Surface condition of this device may change when organic solvents such as trichloroethylene or acetone were applied.

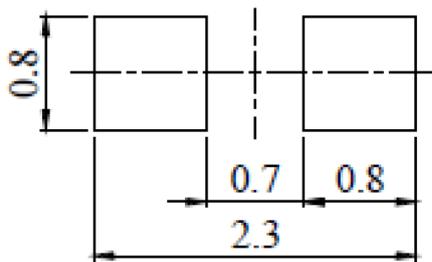
Avoid using organic solvent.

Recommend ultrasonic method 300W Max.

Reflow Temp/Time



Reflow Soldering Pad Dimensions



Part Number Table

Description	Part Number
Chip LED, Super Red, 632nm, 130°, 90mcd, Surface Mount	MP008251

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